



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



3A, 200V Surface Mount Ultra Fast Rectifier

FEATURES

- Glass passivated chip junction
- Ideal for automated placement
- Super fast recovery time for high efficiency
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- High frequency rectification
- Freewheeling application
- Switching mode converters and inverters in computer, automotive and telecommunication.

MECHANICAL DATA

- Case: DO-214AB (SMC)
- Molding compound meets UL 94V-0 flammability rating
- Part no. with suffix "H" means AEC-Q101 qualified
- Packing code with suffix "G" means green compound (halogen-free)
- Moisture sensitivity level: level 1, per J-STD-020
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: As marked
- Weight: 0.21 g (approximately)

KEY PARAMETERS		
PARAMETER	VALUE	UNIT
$I_{F(AV)}$	3	A
V_{RRM}	200	V
I_{FSM}	100	A
$T_{J\ MAX}$	150	°C
Package	DO-214AB (SMC)	
Configuration	Single die	



DO-214AB (SMC)

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)			
PARAMETER	SYMBOL	ES3DV	UNIT
Marking code on the device		ES3DV	
Repetitive peak reverse voltage	V_{RRM}	200	V
Reverse voltage, total rms value	$V_{R(RMS)}$	140	V
Maximum DC blocking voltage	V_{DC}	200	V
Forward current	$I_{F(AV)}$	3	A
Surge peak forward current, 8.3 ms single half sine-wave superimposed on rated load per diode	I_{FSM}	100	A
Junction temperature	T_J	- 55 to +150	°C
Storage temperature	T_{STG}	- 55 to +150	°C

THERMAL PERFORMANCE

PARAMETER	SYMBOL	LIMIT	UNIT
Junction-to-lead thermal resistance per diode	$R_{\theta JL}$	17	°C/W
Junction-to-ambient thermal resistance per diode	$R_{\theta JA}$	50	°C/W

ELECTRICAL SPECIFICATIONS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	SYMBOL	TYP.	MAX.	UNIT
Forward voltage per diode ⁽¹⁾	$I_F = 3\text{A}$, $T_J = 25^\circ\text{C}$	V_F	-	0.9	V
Reverse current @ rated V_R per diode ⁽²⁾	$T_J = 25^\circ\text{C}$	I_R	-	10	μA
	$T_J = 100^\circ\text{C}$		-	500	μA
Junction capacitance	1 MHz, $V_R = 4.0\text{V}$	C_J	45	-	pF
Reverse recovery time	$I_F = 0.5\text{A}$, $I_R = 1.0\text{A}$ $I_{RR} = 0.25\text{A}$	t_{rr}	-	20	ns

Notes:

1. Pulse test with $PW = 0.3\text{ ms}$
2. Pulse test with $PW = 30\text{ ms}$

ORDERING INFORMATION

PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING
ES3DV	H	R7	G	SMC	850 / 7" Plastic reel
		R6		SMC	3,000 / 13" Paper reel
		M6		SMC	3,000 / 13" Plastic reel
		V7		Matrix SMC	850 / 7" Plastic reel
		V6		Matrix SMC	3,000 / 13" Plastic reel

EXAMPLE

EXAMPLE P/N	PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION
ES3DVHR7G	ES3DV	H	R7	G	AEC-Q101 qualified Green compound

CHARACTERISTICS CURVES

($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig.1 Forward Current Derating Curve

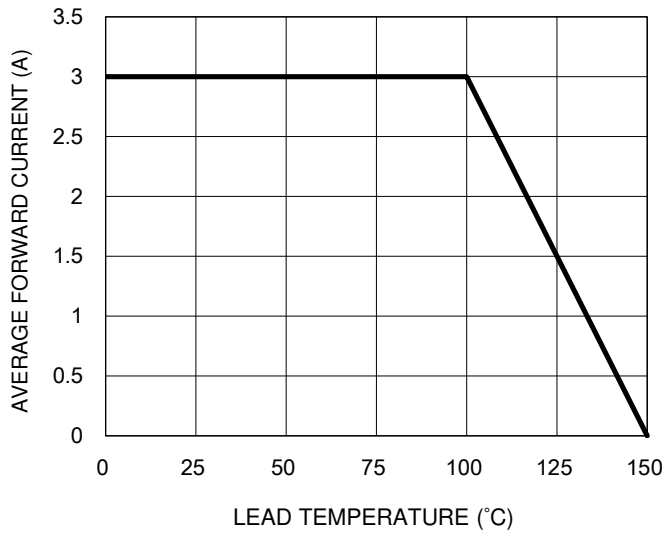


Fig.2 Typical Junction Capacitance

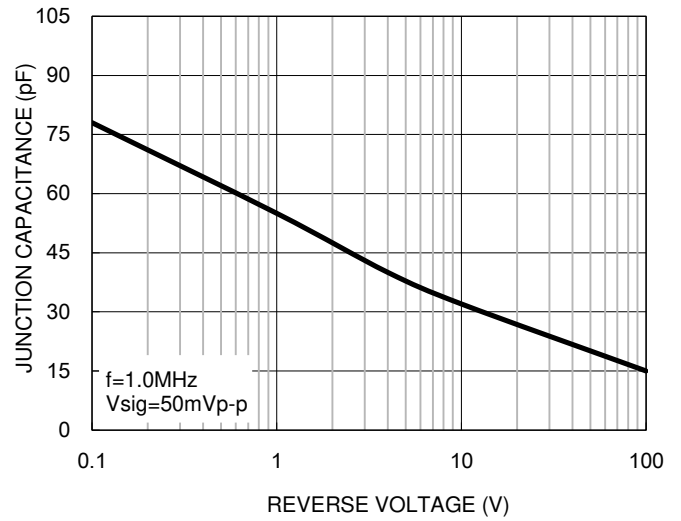


Fig.3 Typical Reverse Characteristics

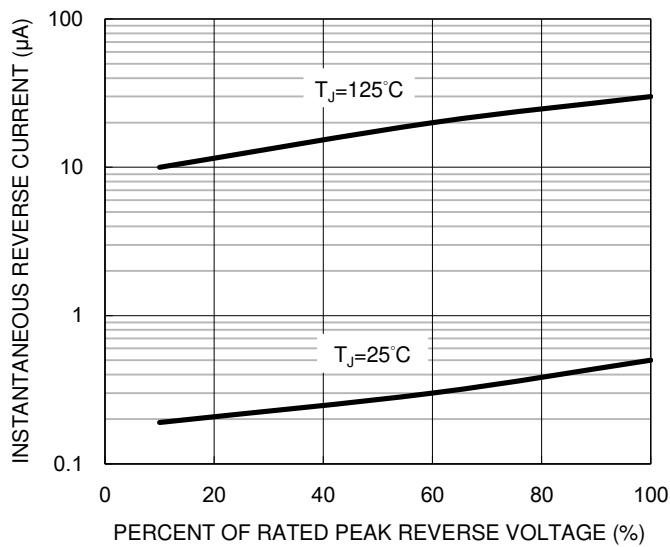
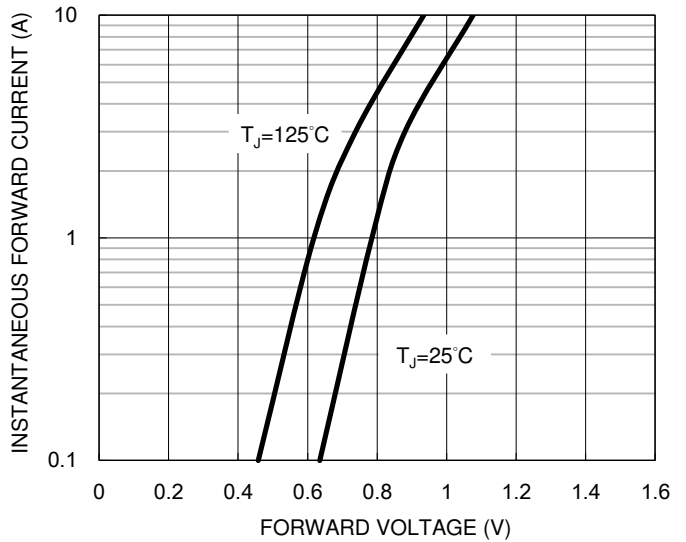


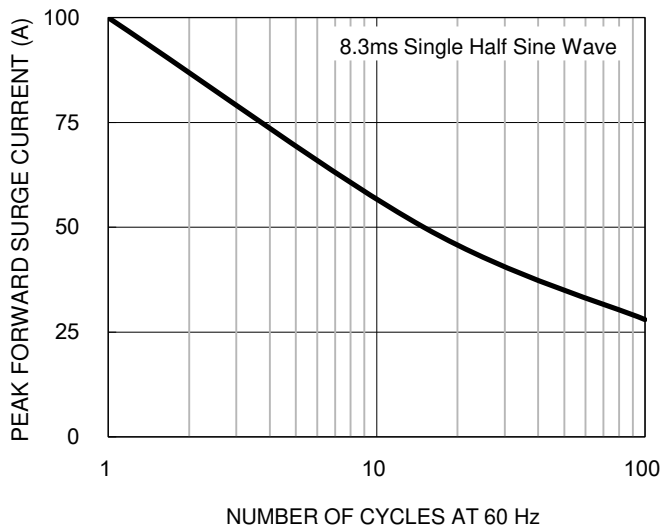
Fig.4 Typical Forward Characteristics



CHARACTERISTICS CURVES

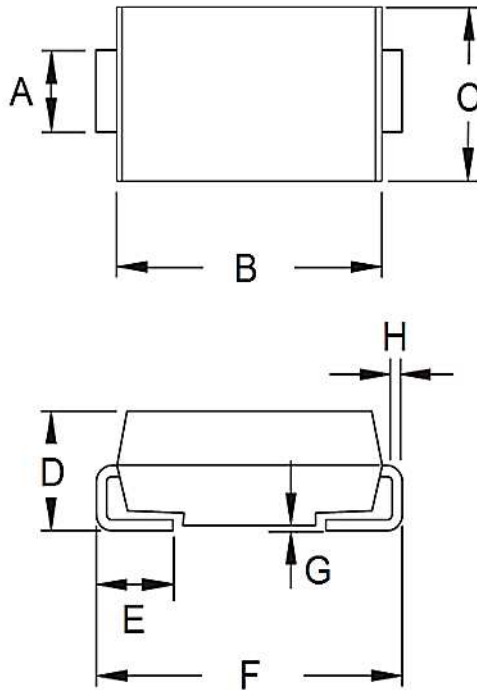
($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig.5 Maximum Non-repetitive Forward Surge Current



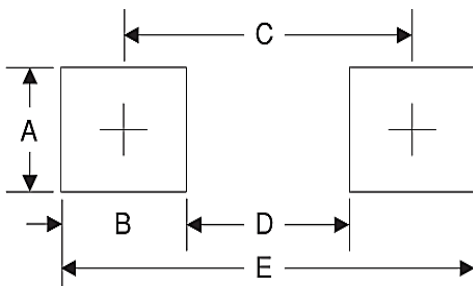
PACKAGE OUTLINE DIMENSIONS

DO-214AB (SMC)



DIM.	Unit (mm)		Unit (inch)	
	Min.	Max.	Min.	Max.
A	2.90	3.20	0.114	0.126
B	6.60	7.11	0.260	0.280
C	5.59	6.22	0.220	0.245
D	2.00	2.62	0.079	0.103
E	1.00	1.60	0.039	0.063
F	7.75	8.13	0.305	0.320
G	0.10	0.20	0.004	0.008
H	0.15	0.31	0.006	0.012

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	3.30	0.130
B	2.50	0.098
C	6.80	0.268
D	4.40	0.173
E	9.40	0.370

MARKING DIAGRAM



P/N =Marking Code
G =Green Compound
YW =Date Code
F =Factory Code

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